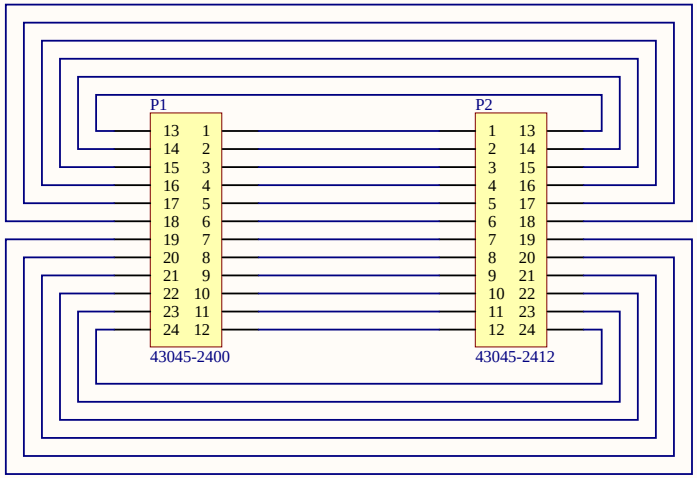
Breakout Board

Rev 1

Title	***Breakout Board***		*Badgerloop* *133 Engineering Research Building* *Madison, WI 53715*
Size: A4	Number:1	Revision:1	
Date: 2/15/2020	Time: 12:14:16 PM	Sheet 1 of	
File: C:\Users\Windows PC\Desktop\Badgerloop\git_repos\hardware\breakout_board\breakout_board.SchDoc			

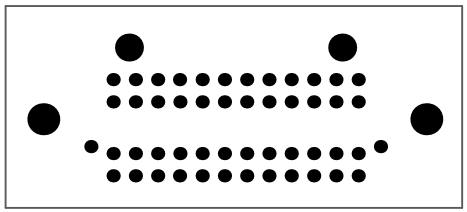
Breakout Board Connectors



MH1
4-40 Mount Hole

MH2
4-40 Mount Hole

Title *Connectors*		Badgerloop Electrical 133 Engineering Research Building 1500 Engineering Drive Madison, WI 53706
Engineer: Andrew Cook	Revision: 1	
Date: 2/15/2020 Time: 12:14:16 PM	Sheet 2 of 1	
File: connectors.SchDoc		



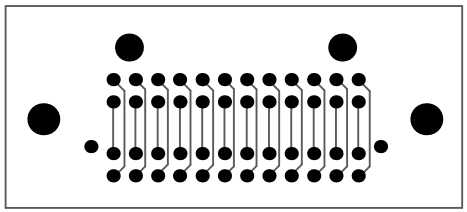
Layer	Name	Material	Thickness	Constant	Board Layer Stack
1	Top Overlay				
2	Top Solder	Solder Resist	0.40mil	3.5	
3	Top Layer	Copper	1.40mil		
4	Dielectric 1	FR-4	12.60mil	4.8	
5	Internal Plane 1	Copper	1.40mil		
6	Dielectric2	FR-4	12.60mil	4.8	
7	Internal Plane 2	Copper	1.40mil		
8	Dielectric3	FR-4	12.60mil	4.8	
9	Bottom Layer	Copper	1.40mil		
10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Top Layer

BADGER LOOP

Badgerloop
ERB Room 133
1400 Engineering Drive
Madison, WI 53706

ENGINEER: Andrew Cook	TITLE: breakout_board.PcbDoc		
PCB DESIGNER: Andrew Cook			
DATE: 2/15/2020	PART NO.: Battery Module Breakout Board	REV: A	
FILE NAME: breakout_board.PcbDoc	DWG NO:	SCALE: 1:1	



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10	Bottom Solder	Solder Resist	0.40mil	3.5	
11	Bottom Overlay				

Bottom Layer

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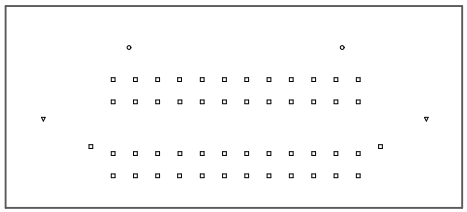
Symbol	Count	Hole Size	Plated	Hole Type	Drill Layer Pair	Via/Pad	Pad Shape	Template
□	50	40.00mil (1.016mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c178h102
▽	2	116.00mil (2.946mm)	NPTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c430hn295
○	2	118.00mil (2.997mm)	PTH	Round	Top Layer - Bottom Layer	Pad	Rounded	c376h300
	54 Total							



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